

The Capacitive Division Image Readout; An imaging technique combining high time and spatial resolution

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Presentation Overview

- INTRODUCTION....system overview
- DESIGN, SIMULATION AND MANUFACTURE....of C-DIR
- EXPERIMENTS AND RESULTS....for C-DIR
- CONCLUSIONS

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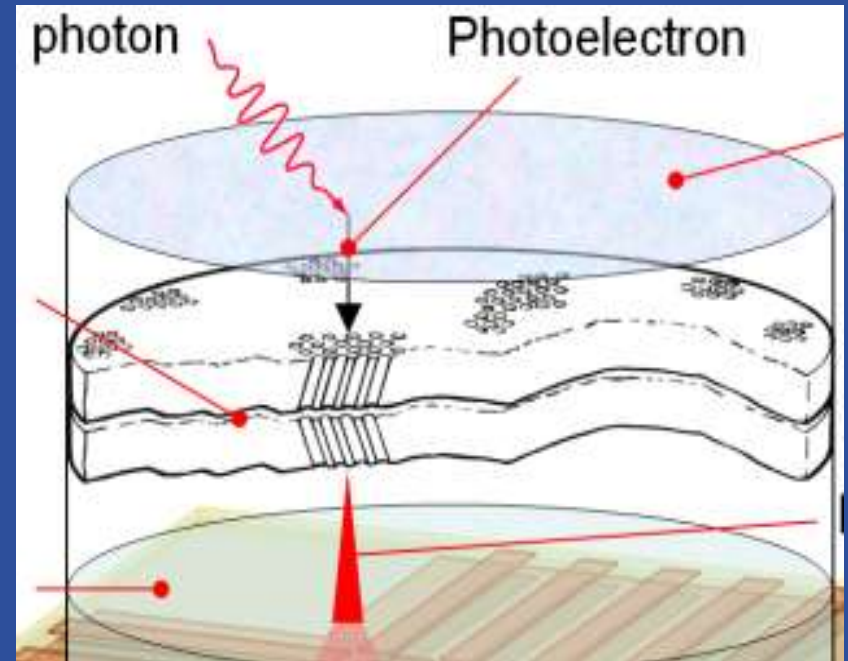
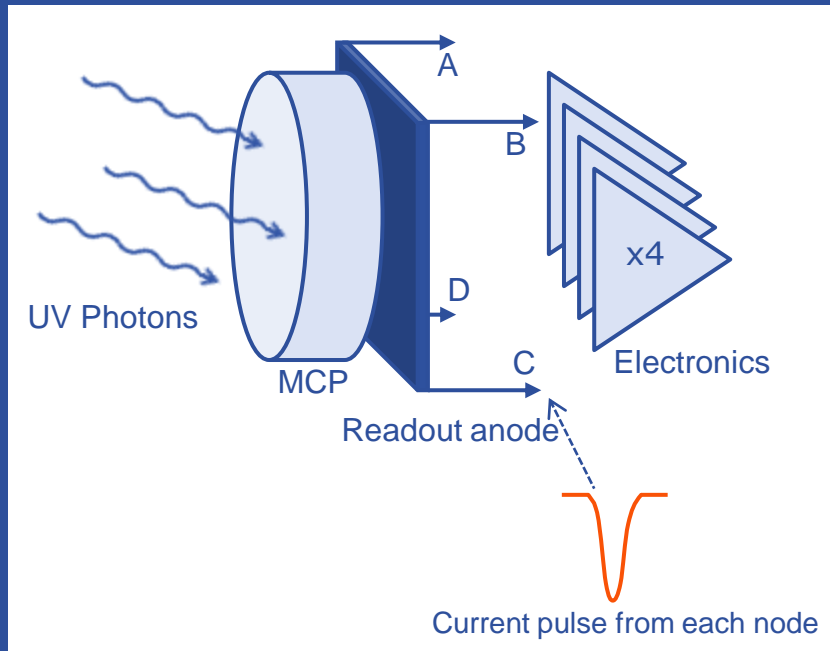
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INTRODUCTION

System overview: MCP detector, readout & analogue electronics.



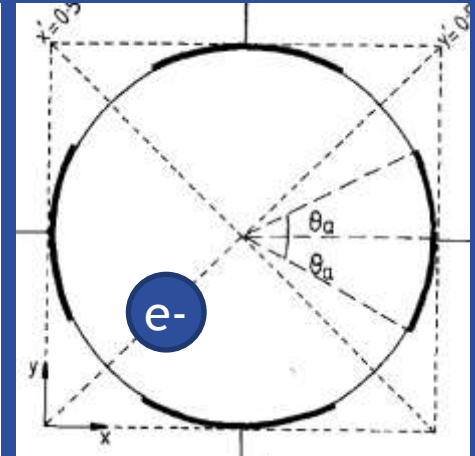
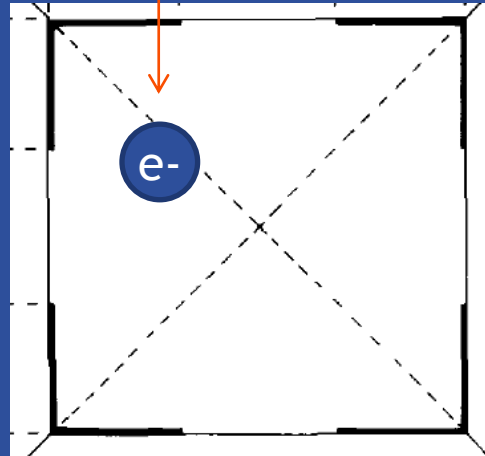
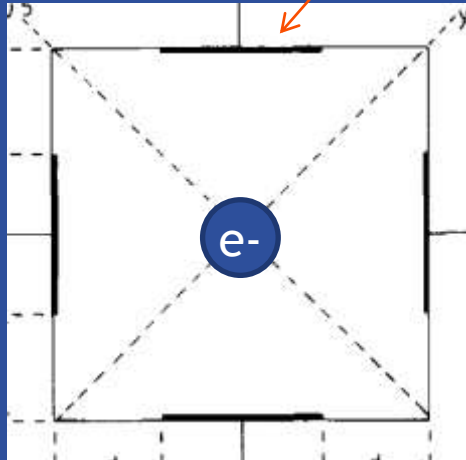
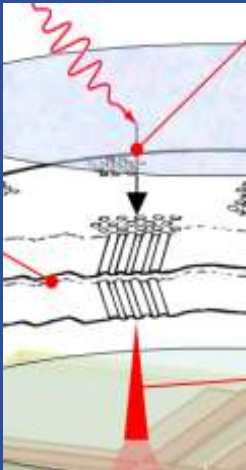
Electron cascade through Microchannel Plate and electron cloud incident on readout anode for measurement.

MCP stack run in high gain, saturated, mode. $>10^6$ electrons.

INTRODUCTION

$$x = \frac{(A+D)}{(A+B+C+D)}, \quad y = \frac{(A+B)}{(A+B+C+D)}$$

Charge division - Charge centroid centre of gravity encodes the 2-D coordinate of the event. Dividing charge among a small number of instrumented nodes. Charge amplitudes are measured and an algorithm used to decode event position coordinate.



Fraser (1980&81)

Several methods can be used to divide the charge amongst the measurement nodes:

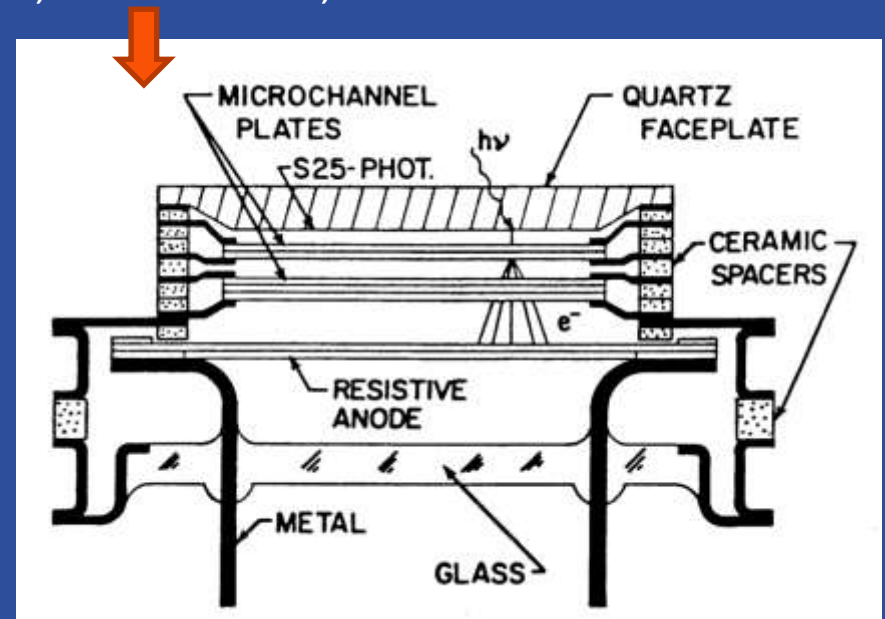
- Resistive
- Geometric
- Capacitive division

INTRODUCTION: Resistive division

- Resistive anode, popular technique.
- Event charge cloud collected on resistive sheet $\sim 10 \text{ k}\Omega$ to $1 \text{ M}\Omega$ per square.
- Charge resistively divided amongst four perimeter contacts, electronically measured and event coordinate calculated using an algorithm such as:

$$x = \frac{Q_A + Q_B}{Q_A + Q_B + Q_C + Q_D} \quad y = \frac{Q_B + Q_C}{Q_A + Q_B + Q_C + Q_D}$$

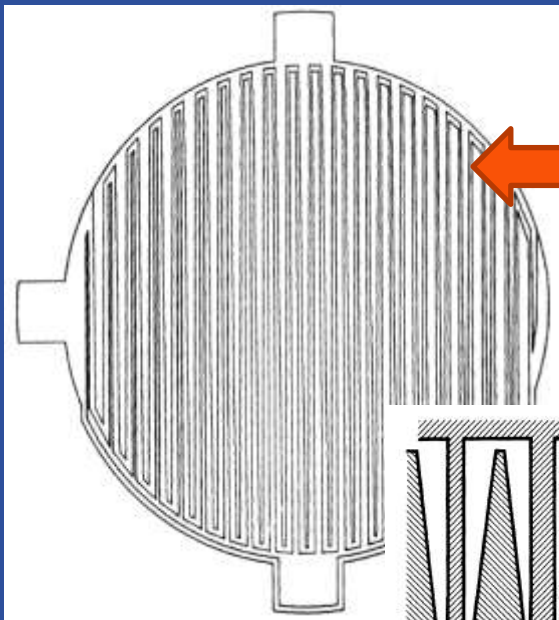
- Ground based and space based applications; the RANICON, ROSAT WFC and EXOSAT
- Resolution dominated by two noise components; resistive thermal noise or 'Johnson' noise & pre-amplifier noise.
- Limits resolution to several tens of μm .
- Timing restricted (RC).



Lampton (1974)

INTRODUCTION: Geometric division

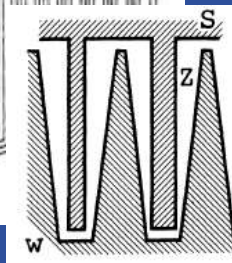
- E.g. wedge and strip anode (WSA). Small number of interleaved conductive electrodes to collect the charge. Modulation of the electrode areas to charge ratio.
- Inherently faster than resistive (conductive electrodes).
- Interleaved nature can cause a) higher electrode resistance b) high inter-electrode capacitance (more noise) c) dynamic image drifts due to redistribution of SE.



Lapington (1986)

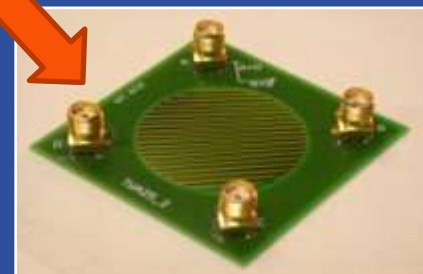
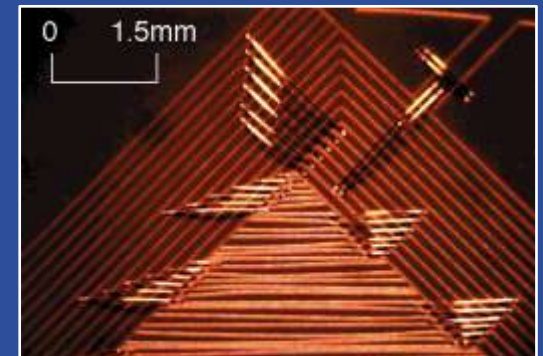
Examples:

- Wedge Strip Anode
- Vernier Anode
- Tetra Wedge Anode



$$X = \frac{2Q_S}{Q_W + Q_S + Q_Z}$$

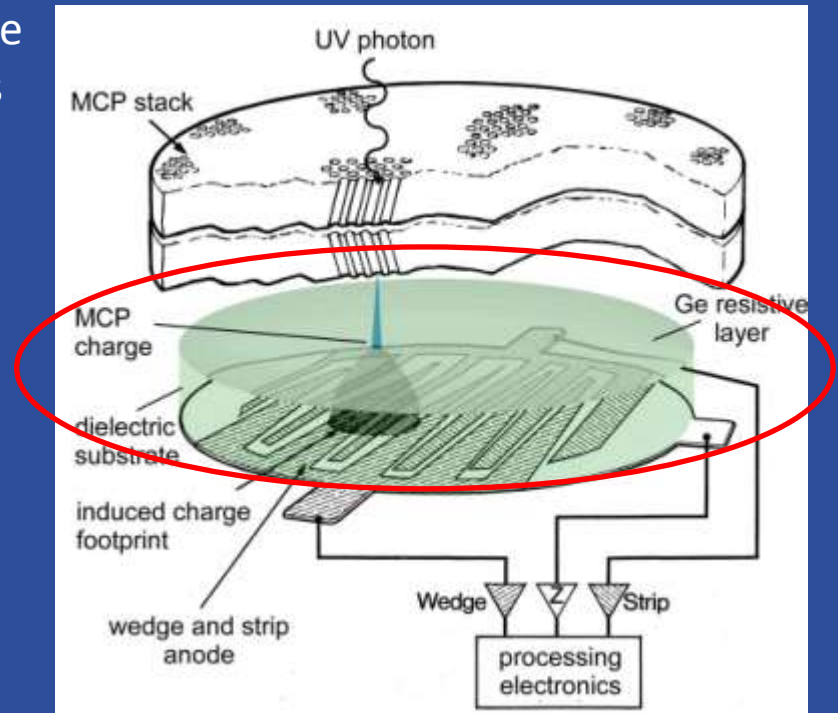
$$Y = \frac{2Q_W}{Q_W + Q_S + Q_Z}$$



INTRODUCTION:

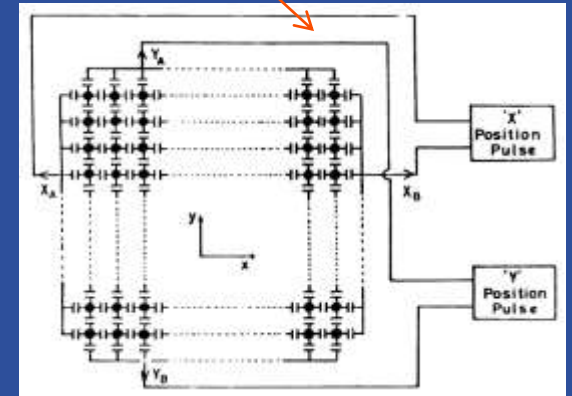
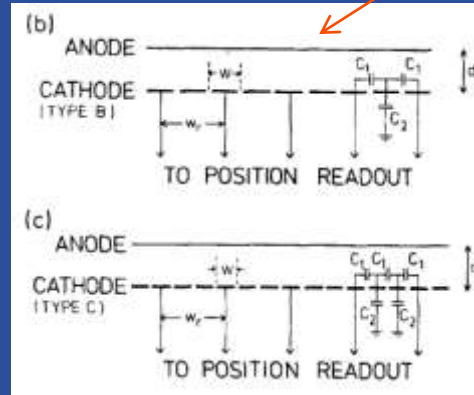
A note on Image Charge.....

- Charge cloud is collected on a passive resistive anode coupled to a conductive readout such as a WSA via a dielectric substrate.
- Resistive layer physically localises the charge while the readout detects the signal transient induced through the dielectric.
- Signal charge slowly leaks away through the resistive layer.
- Removes SE redistribution, constant charge footprint, avoids the partition noise.
- Allows readout to be operated at ground irrespective of the detector anode voltage.



INTRODUCTION: Capacitive division

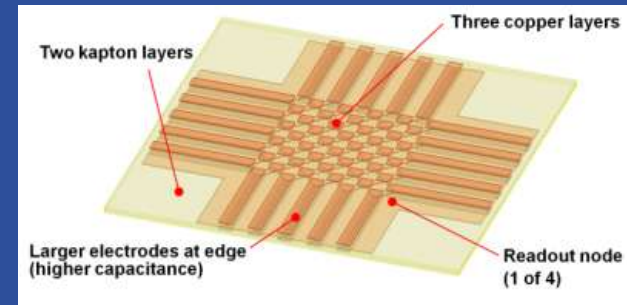
- Capacitive division experimentally demonstrated before. Gott(1970); 2-D square array via wires to an separate capacitor network . Smith(1988); array of 1-D strip electrodes to charge share. Drawbacks; discrete capacitors, parasitic capacitance, bulky, engineering complexity.



Development of a capacitive division readout:

Capacitive Division Image Readout (C-DIR)

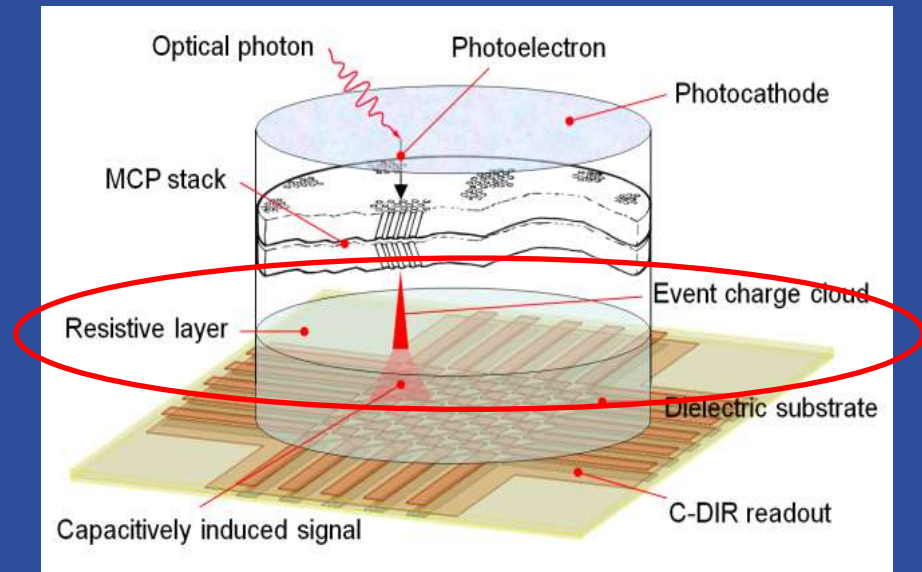
- 2-D array of isolated electrodes which divide the signal via their mutual capacitance to four measurement nodes at four corners of the readout.



DESIGN, SIMULATION AND MANUFACTURE: C-DIR

Stage 1: Resistive Anode

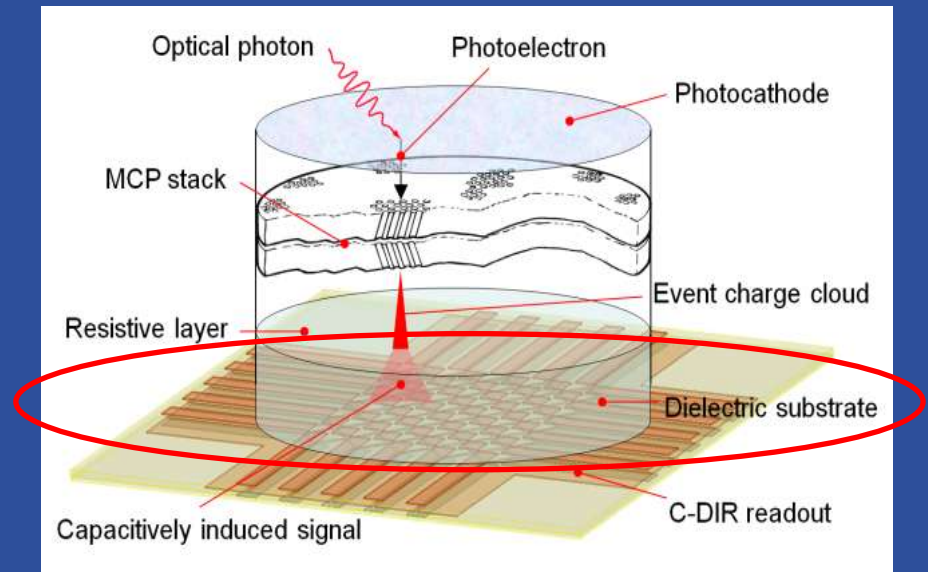
- Charge collected by the resistive anode (electrodes do not need to be resistively coupled).
- Resistive layer localizes charge, signal transient couples through dielectric.
- RC time constant has no influence on the transient signal.
- SE redistribution of the primary event charge occurs but its footprint is symmetric, stable and predictable.



DESIGN, SIMULATION AND MANUFACTURE: C-DIR

Stage 2: Dielectric Substrate

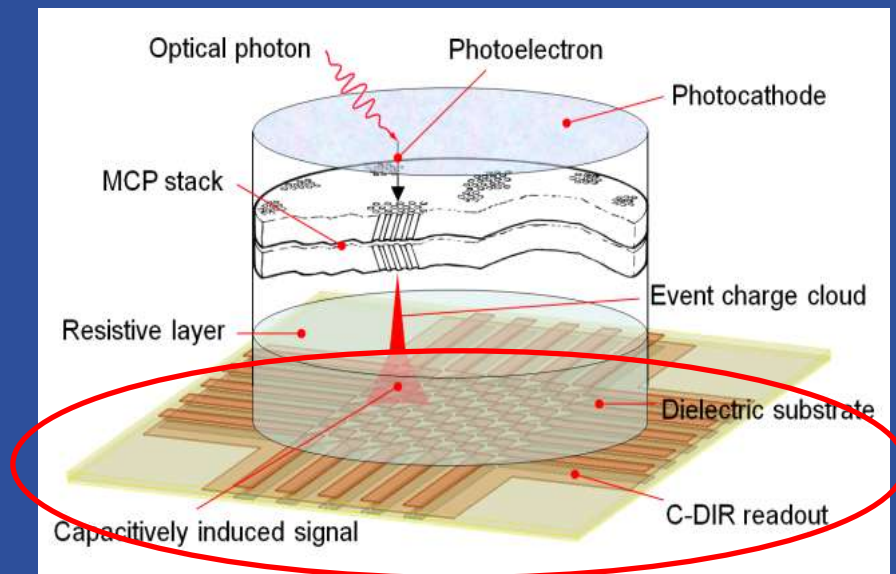
- Alumina dielectric layer (typ. 2 mm thick) supports the RA (thickness defines footprint).
- Stands off detector high voltage.
- Acts as the rear vacuum vessel wall, readout completely outside the vacuum environment, no feedthroughs required.
- Only resistive layer connection, through perimeter via its metallic support flange.



DESIGN, SIMULATION AND MANUFACTURE: C-DIR

Stage 3: Readout

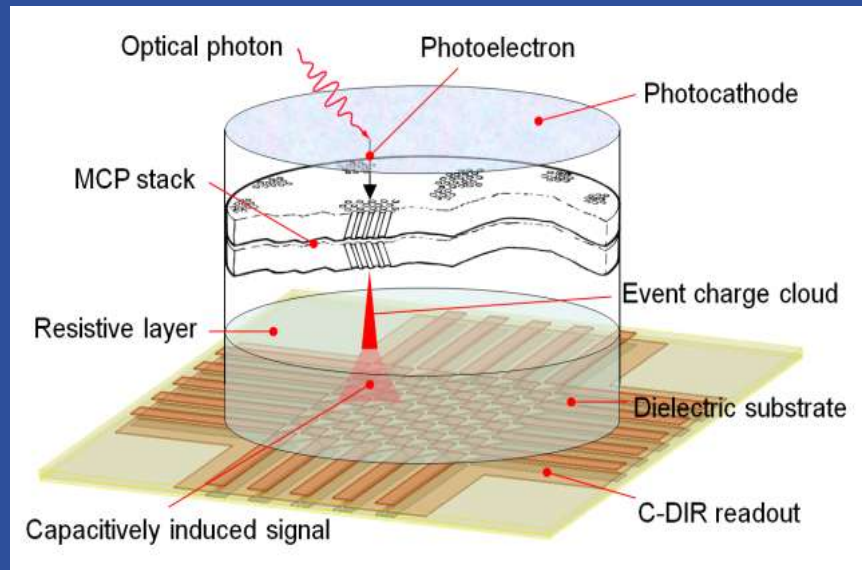
- Simple passive, multilayer PCB
- Matrix of isolated electrodes, geometry defines the mutual capacitances.
- Signal charge induced is capacitively shared among the four charge measurement nodes.
- Intrinsic capacitance array minimizes parasitic capacitance, <noise, >resolution.
- Minimize dominant parasitic capacitance (MCP output face) to <10% by detector geometry and dielectric choice.
- Array capacitance small => preamplifier input load <5 pF (25 mm²) (cf. 40-70 pF comparable WSA).
- Capacitive signal chain: Very high bandwidth, extract position & event time resolution in the sub-100 ps range.
-more



DESIGN, SIMULATION AND MANUFACTURE: C-DIR

...Stage 3 cont: Readout

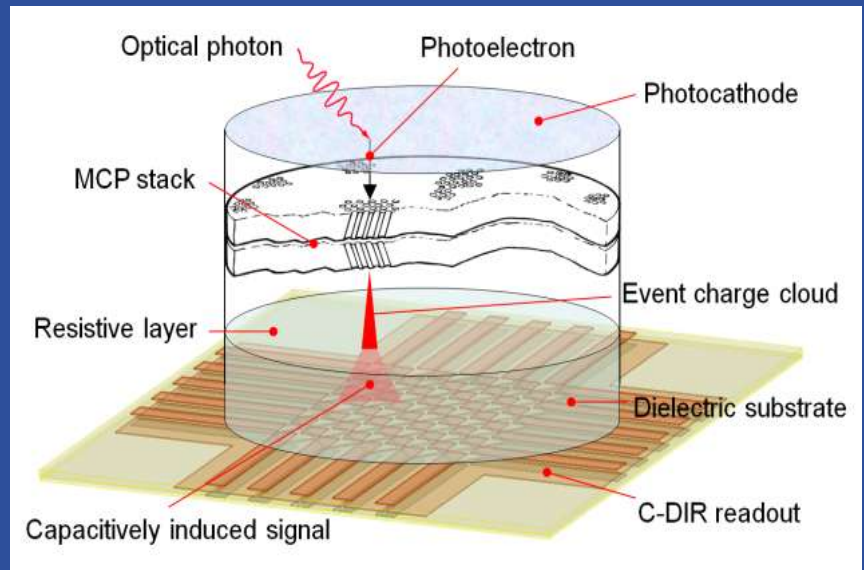
- Exploits full dynamic range of all 4 electrodes (cf. WSA <33% of the signal).
- Predictability of footprint distribution allows precision optimization of readout electrode array pitch and linearity control.
- Outside the vacuum (hermetically sealed from sensitive internals) => readout requires standard PCB materials and manufacturing techniques => low risk and economical.



DESIGN, SIMULATION AND MANUFACTURE: C-DIR

Overall

- C-DIR components manufactured using robust, well characterized, radiation-hard materials.

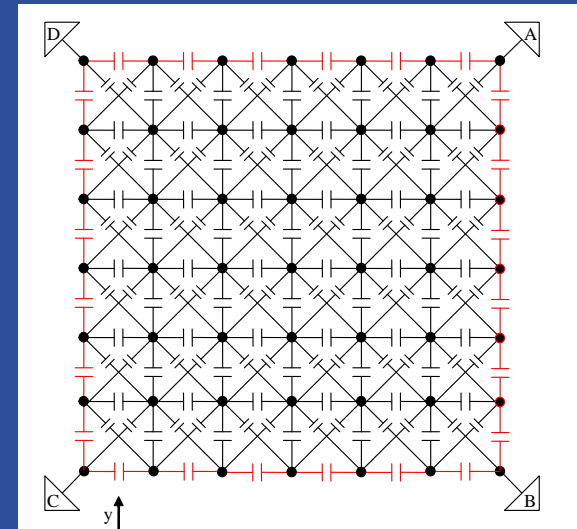
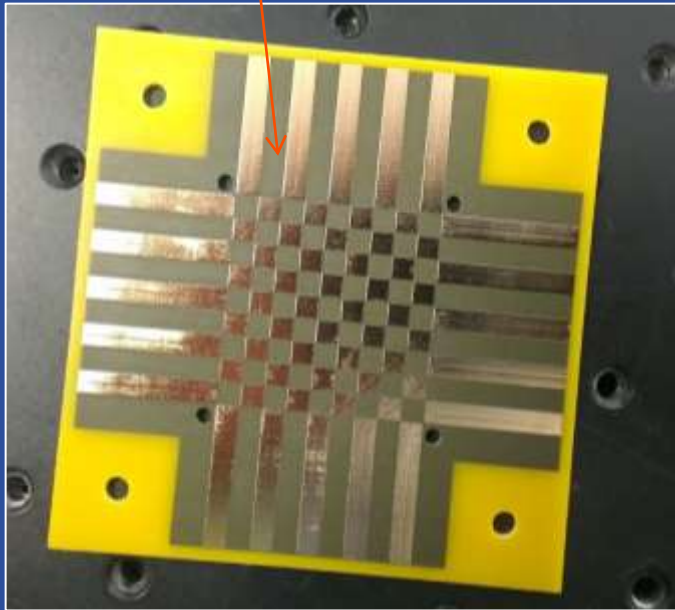


Manufacture

- Resistive layer; thick film screen printing technology.
- Robust alumina dielectric substrate.
- Conventional PCB readout.
- C-DIR; simple surface contact with the rear face of the alumina dielectric.

DESIGN, SIMULATION AND MANUFACTURE: C-DIR

- Original design analogous to resistive anode; uniform low value capacitive coupling surrounded by perimeter of higher capacitance (for linearity) achieved by modulating the area of the perimeter electrodes.

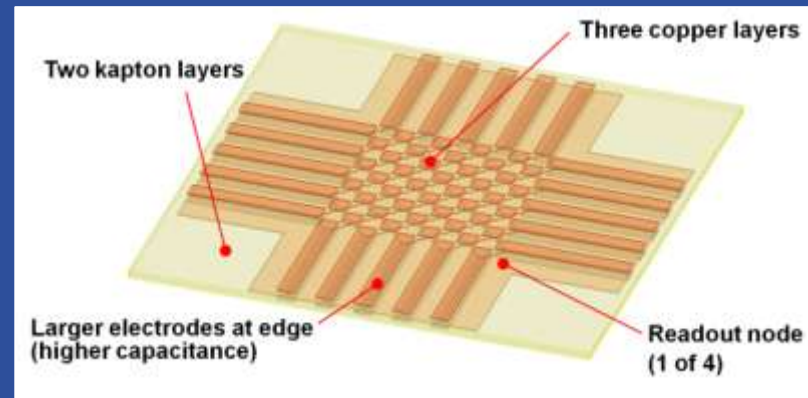
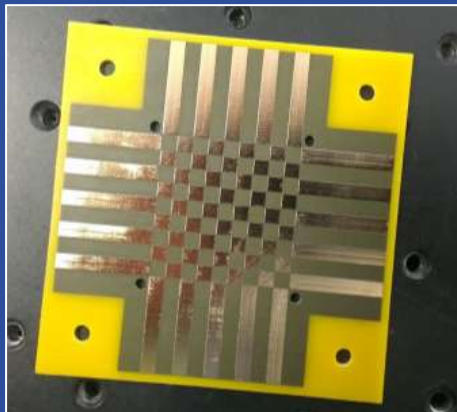


- Optimized 25 mm active area C-DIR.
- Comprises three layers of isolated conductors separated by thin insulator.
- Overlap between conductors on adjacent layers defines the mutual capacitances.
- Only 10 pattern pitches (2.54 mm); sharing of the induced signal between multiple electrodes => centroid footprint.

DESIGN, SIMULATION AND MANUFACTURE: C-DIR

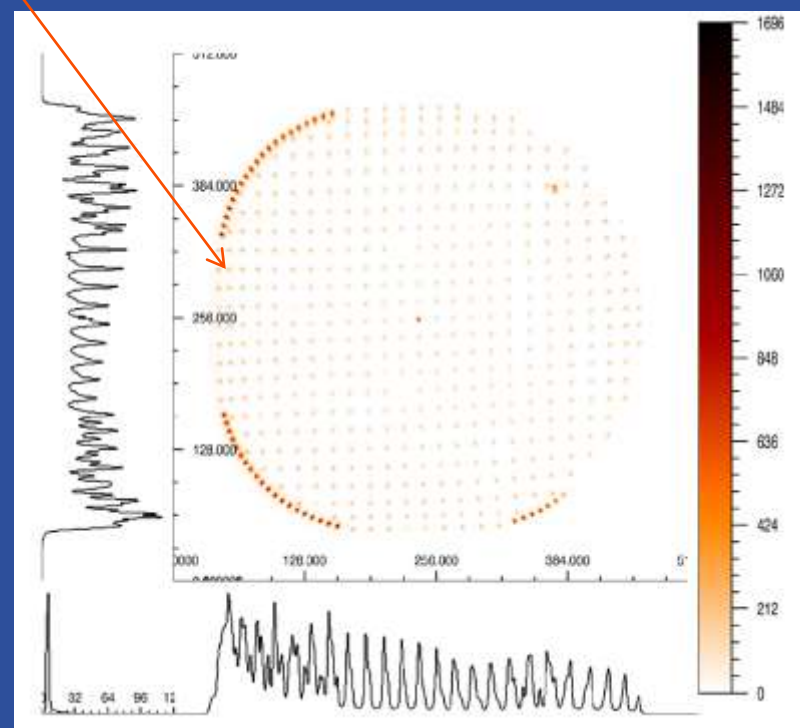
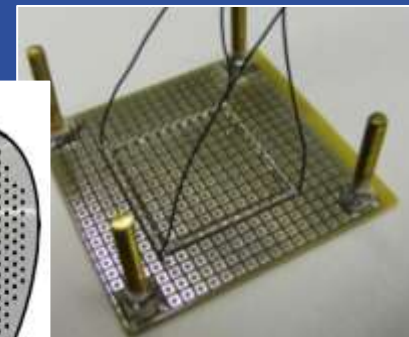
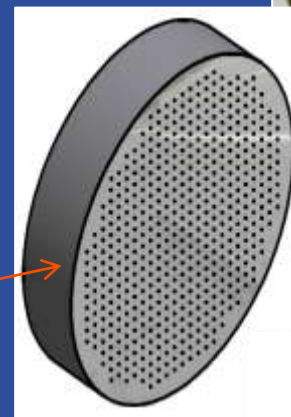
Advantage summary:

- Capacitive nature avoids partition noise (physical collection of quantized charge carriers).
- Avoids serial resistive noise.
- DC signal discharge current (resistive anode) has no influence on the readout signal timescales.
- Dominant remaining noise; capacitive load on each preamplifier is very low.
- Pattern-edge geometry optimization => ~90% linear dynamic range.
- Resulting spatial resolution >2000 x 2000 pixel² (using ultra low noise electronics).



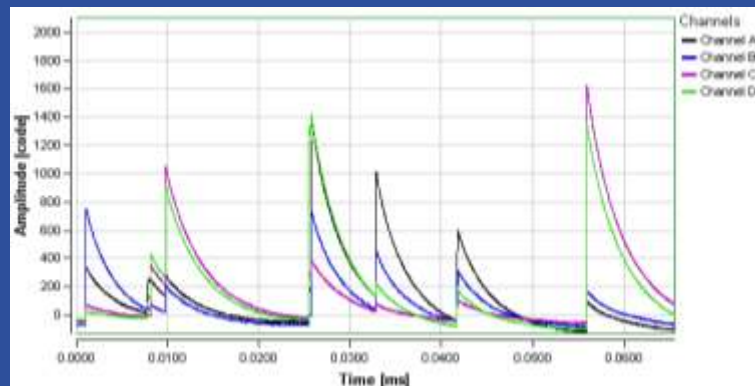
EXPERIMENTS AND RESULTS

- Prototype C-DIR device; PCB, double-sided array of conductive square pads, 2.54 mm pitch.
- Pinhole array mask image (25 μm & central 50 μm diameter pinholes).
- Spatial resolution 150 μm FWHM @ $\sim 10^6$ electrons.
- Proved concept, measured performance limited:
 - Signal loss to the rear MCP contact by parasitic capacitance.
 - Coaxial cable to the CSP => dominant capacitive load.
 - Optical broadening of image on detector PC (source collimation and diffraction).



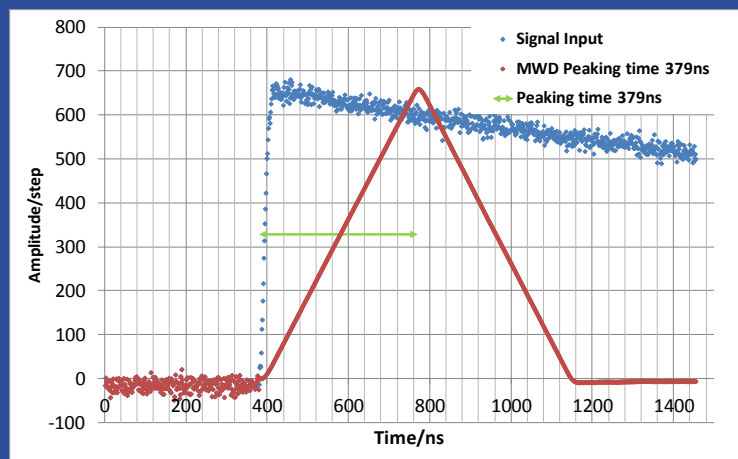
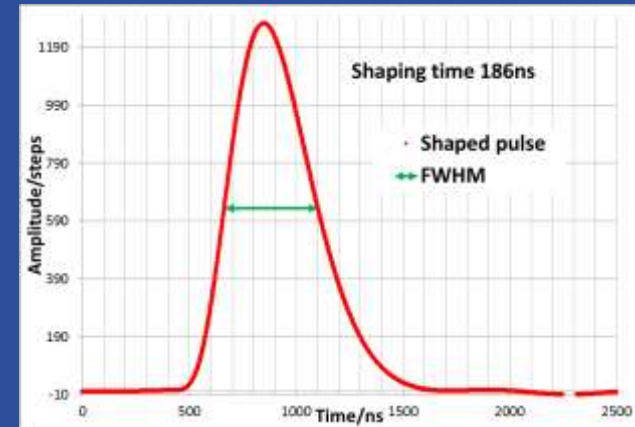
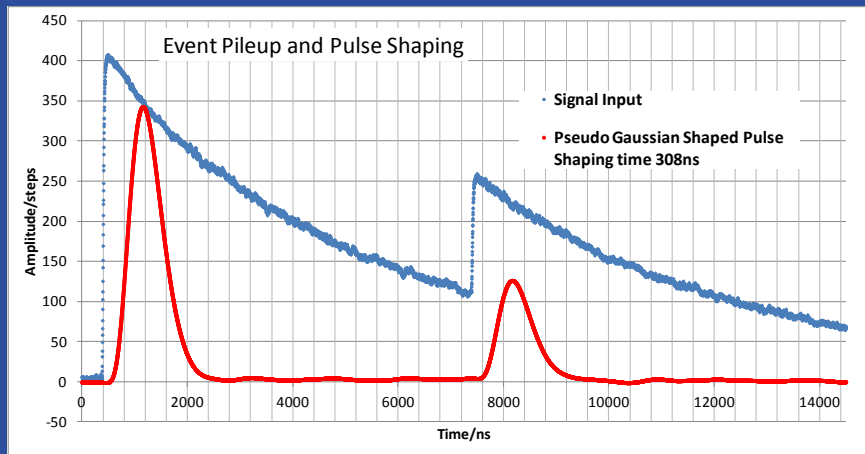
EXPERIMENTS AND RESULTS: Adaptive electronics

- Investigated variety of configurations of charge measurement electronics.
- Can utilise traditional pulse processing designs (resistive anode, WAS anode, etc.).
- Exploit extended spatial resolution/maximum-count-rate envelope:
 - Use high speed digitisation & adaptive digital filtering (req. ESA JUICE mission).
 - Trade-off between overall count rate and spatial resolution to be dynamically selected to suit science requirements.
- Developed demo laboratory system:
 - C-DIR & MCP close-coupled.
 - Amptek A250 & A275 optimised for high rate or high spatial resolution imaging.

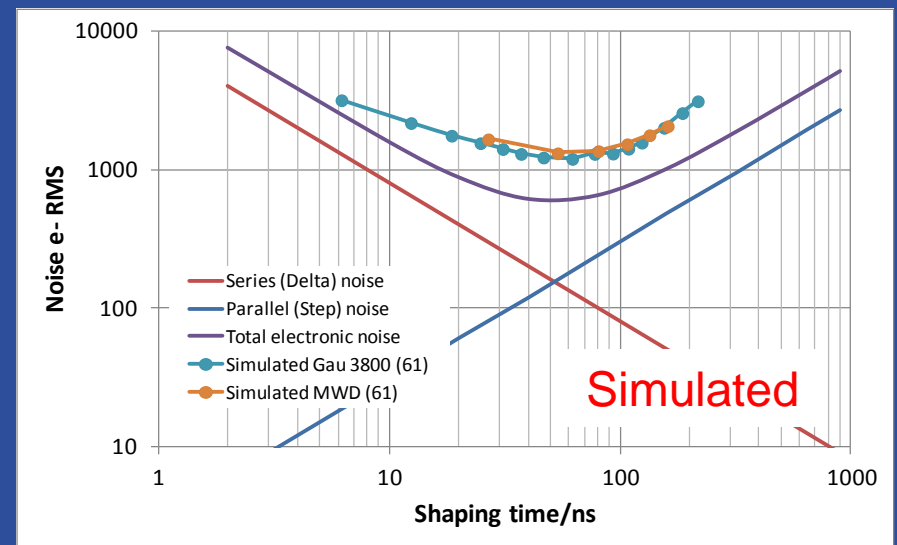


EXPERIMENTS AND RESULTS: Adaptive pulse shaping

- Investigating various filtering schemes digitally encoded (Moving Window Deconvolution, pseudo Gaussian, CR-RCⁿ). Adaptability to count rate.

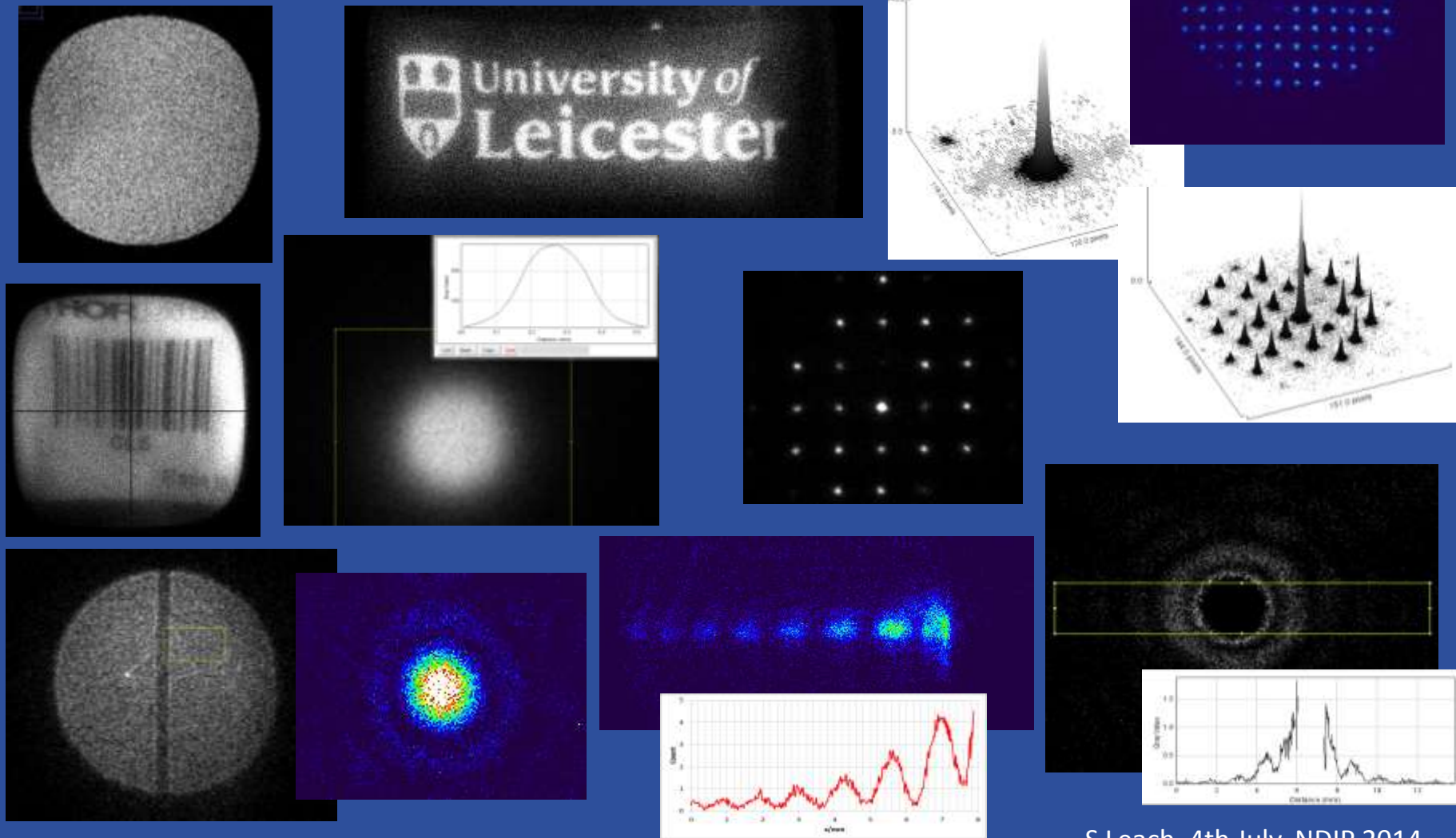


MWD



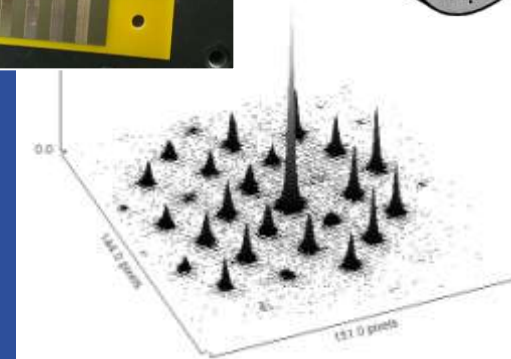
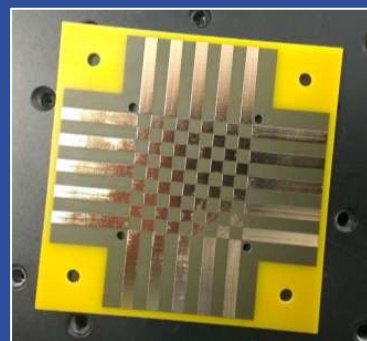
EXPERIMENTS AND RESULTS:

- First imaging results: Aperture, pinhole & array, slit, diffraction and various other photon counting test images.



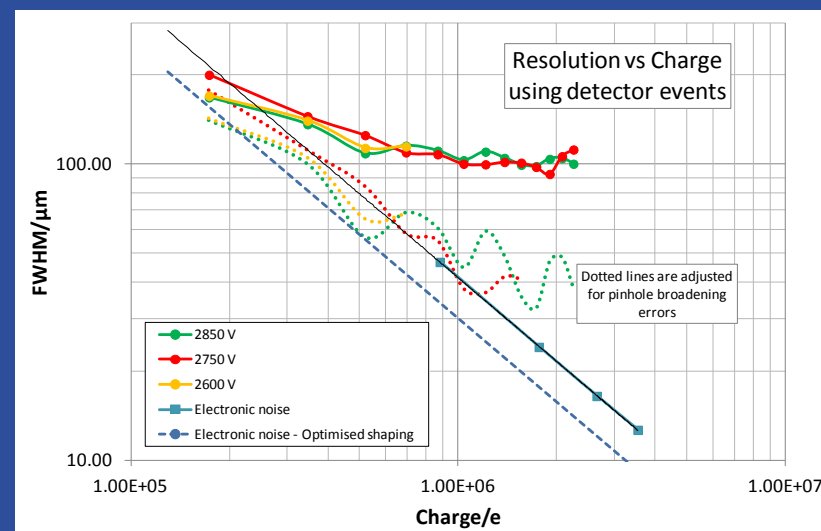
EXPERIMENTS AND RESULTS:

- Optimised 25 mm C-DIR design.
- Collimated light source to pinhole array mask on detector (25 μm & central 50 μm pinholes).
- Measured electronic noise & detector resolution.



Measured electronic noise equates to 7.7 μm at 4.3×10^6 electrons

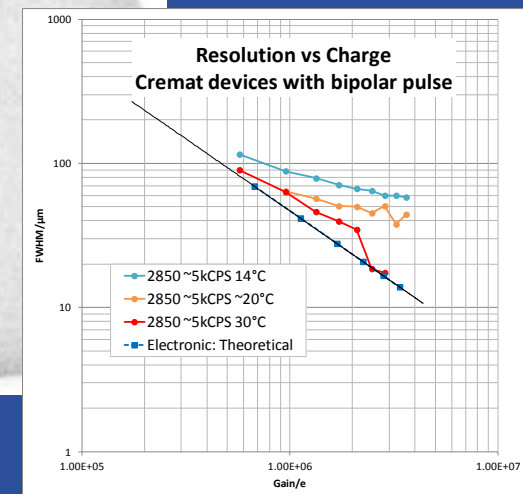
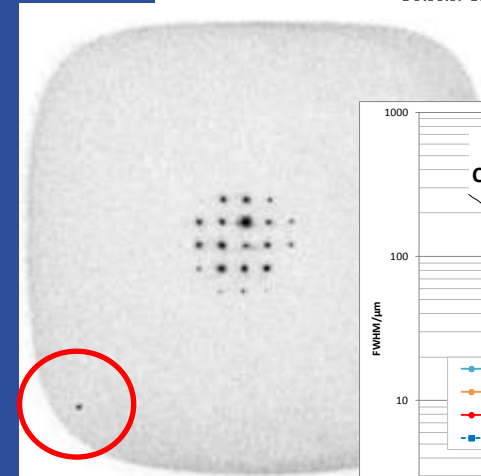
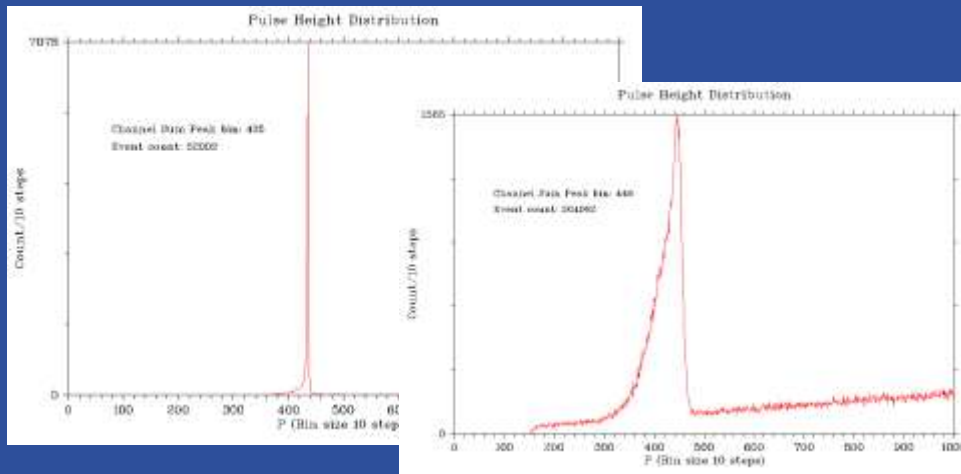
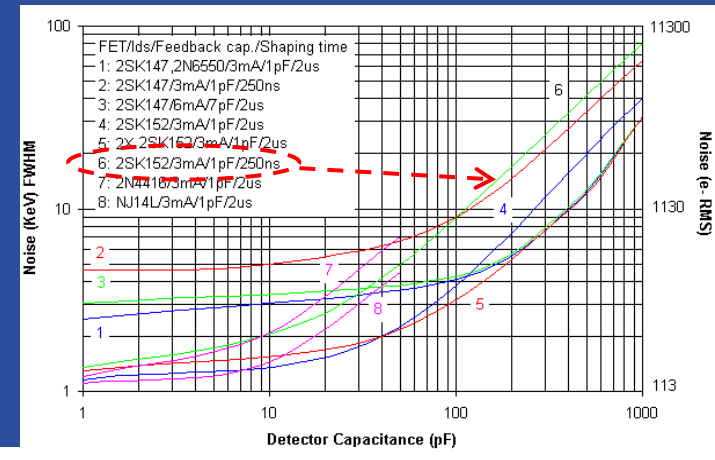
- Measured pinhole width image controlled by:
 - › 50 μm diameter of the pinhole.
 - › Collimator pinhole in front of the LED source.
 - › Distance of the mask from PC (window thickness).
 - › Diffraction (mask pinhole size at the LED λ).
 - › Proximity focus broadening PC & MCP.
 - › Centroiding errors within the MCP stack.
 - › Electronic noise (CME).



EXPERIMENTS AND RESULTS:

Measured electronic noise equates to $7.7 \mu\text{m}$ at 4.3×10^6 electrons.

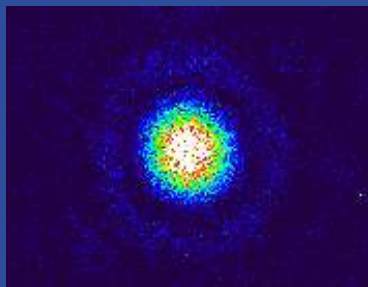
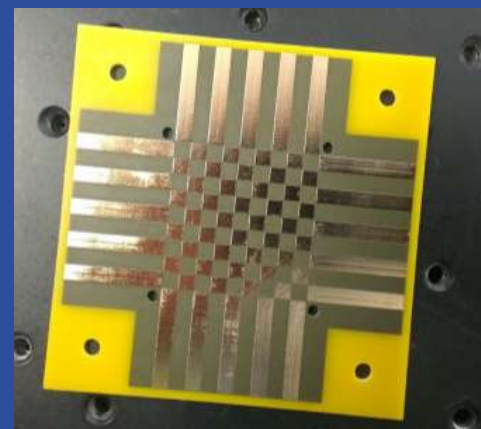
- Translating into spatial resolution is proving challenging:
 - › Low noise amplifiers difficult to reproduce manufacturers specification of 200 e-RMS
 - › Hot spot on sealed tube MCP causing high background limiting signal
 - › Temperature response of MCP plates
 - › Optical path influences
 - › Unipolar signal increasing pulse pileup



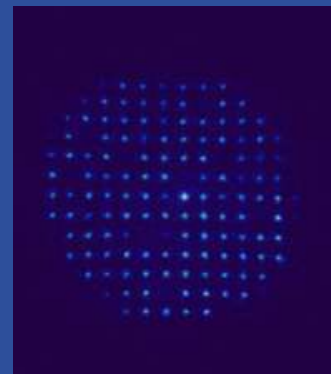
CONCLUSIONS

C-DIR: Capacitive Division Image Readout

- Device is a simple, low cost, easily manufactured.
- Centroiding readout device, only four electronic channels.
- Offers significant performance and operational advantages.
- Imaging performance dominated by electronic noise.
- Low capacitive load, potential resolution of $10\ \mu\text{m}$ FWHM at a gain of $\sim 3 \times 10^6$ electrons.
- Combined imaging and event timing sub 100 ps, close to the limit of the MCP itself.

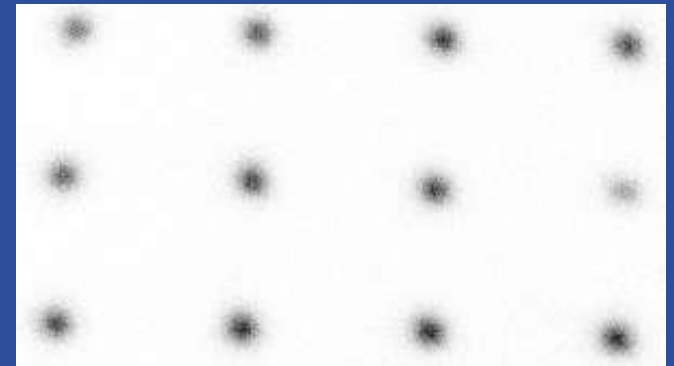
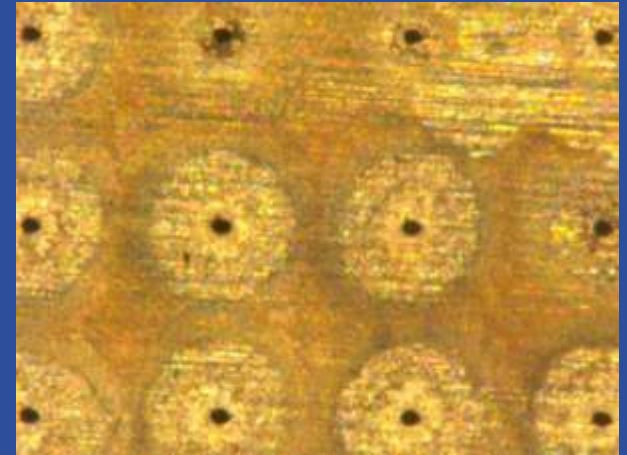


Thank you for listening
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FUTURE IMPROVEMENTS:

- Re-visiting grounding plate of FEE circuit
- Use new bare MCP in vacuum chamber
- Use direct UV, no PC focussing issue
- Expand dynamic range of FEE
- Optimise shaping time
- Rev2 to linearise C-DIR



REFERENCES

Thank you for listening.

Presenter: Steven Leach

Space Research Centre, University of Leicester, UK

For references please see:

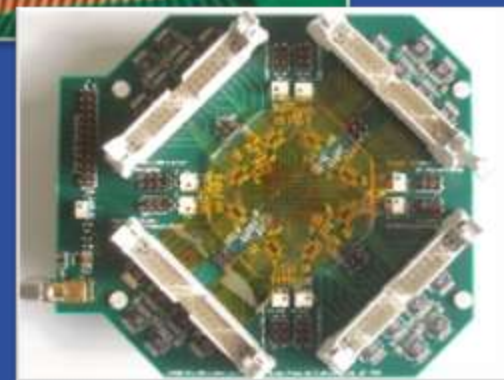
The Capacitive Division Image Readout: A Novel Imaging Device for

Microchannel Plate Detectors: Lapington NDIP 2014 8859 - 32.

EXPERIMENTS: High speed electronics

Another electronic approach:

- Exploit ~ 30 ps event timing of MCP (purely capacitive design, no resistive elements in signal path) \Rightarrow nanosecond shaping times.
- High speed charge measurement \Rightarrow imaging & sub-100 ps event time resolution.
- Count rate capability in the 10 MHz range.
- Applications requiring fast event timing (wide-field fluorescent lifetime imaging) .
- Multi-channel NINO amplifier/discriminator ASIC developed at CERN for the ALICE time-of-flight subsystem.
- High Performance Time to Digital Convertor (HPTDC) ASIC (CERN).
- Combined uses time-over-threshold (TOT) technique for event timing correction $\Rightarrow 25$ ps.

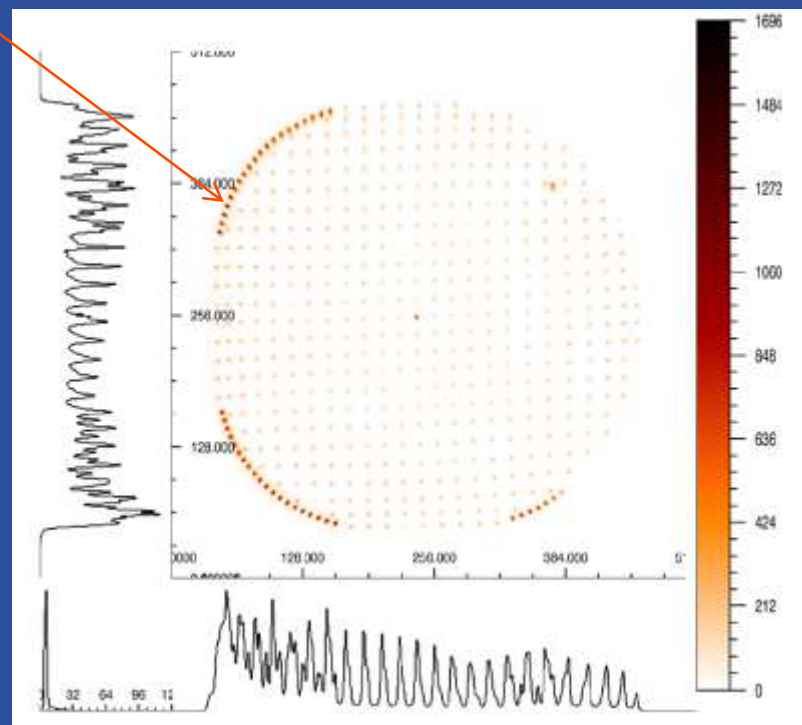
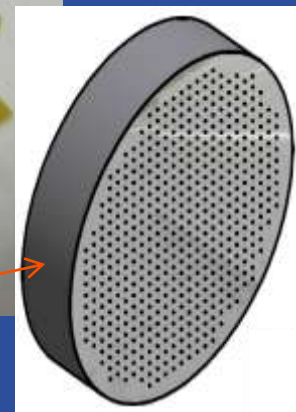
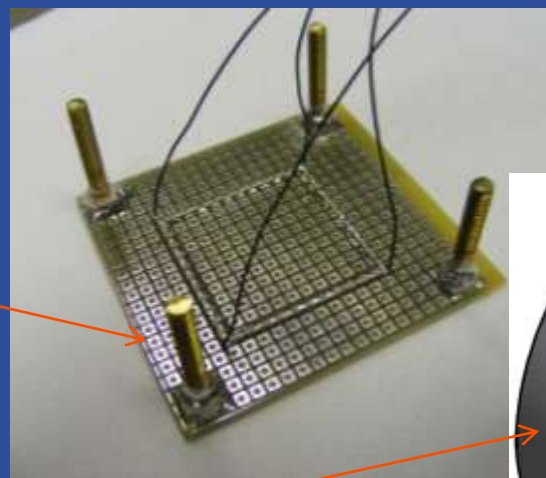


Results and more in paper 8859-32. (Extra...)

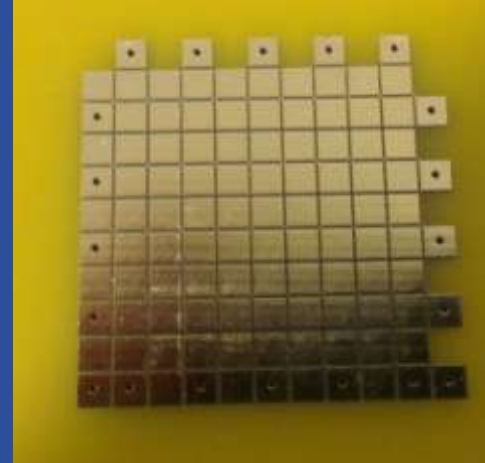
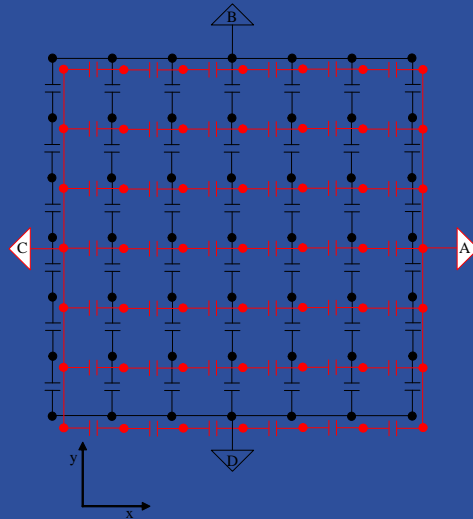
EXTRA..Prototype

- Prototype C-DIR device; PCB, double-sided array of conductive square pads, 2.54 mm pitch.
- Perimeter capacitance achieved with surface mount capacitors.
- Pinhole array mask image (25 μm & central 50 μm diameter pinholes).
- Proved concept, measured performance limited:
 - Signal loss to the rear MCP contact by parasitic capacitance.
 - Coaxial cable to the CSP => dominant capacitive load.
 - Optical broadening of image on detector PC (source collimation and diffraction).

Spatial resolution 150 μm FWHM @
 $\sim 10^6$ electrons.



Extra....C-DIR alternate design



- Alternate design; x and y axes are encoded separately.
- All mutual capacitances define perfect linear dividers; no need for large perimeter capacitances.
- Each axis only benefits from half signal which impacts signal to noise ratio.

Extra....Experimental optical setup

